

IN THE CLAIMS:

The claims below are provided for reference only.

Claims 1-3 (Cancelled).

Claim 4 (Previously Presented): A method of manufacturing a battery pack having a vessel, a battery mounted in the vessel and a circuit board connected to the battery, comprising:

a step of forming a terminal portion in manufacturing the circuit board, the step of forming the terminal portion including stacking a base layer of copper and a plated layer of gold successively to form the terminal portion,

wherein the circuit board is a square-shaped rigid-type printed wiring board made of glass epoxy resin;

a step of forming an insulating layer after the step of forming the terminal portion in manufacturing the circuit board, the step of forming the insulating layer including forming the insulating layer in another area than an area where the terminal portion is formed,

wherein the insulating layer is formed so as to cover a peripheral edge of the plated layer so that the surface of the circuit board and at least one of the surface of the base layer are not exposed externally, and the insulating layer is made of epoxy resin; and

a step of mounting an electronic component after the step of forming the insulating layer, the step of mounting the electronic component including mounting the electronic component on given positions of the circuit board by a solder reflow process.

Claims 5-6 (Cancelled).

Claim 7 (Previously Presented): A method of manufacturing a battery pack according to claim 4, further comprising the steps of:

- forming a base layer of a copper pattern on a surface of an insulating board;
- forming a plated layer so as to cover the entire base layer by selective plating; and
- forming the insulating layer on the plated layer and patterning the insulating layer so that only a portion of the plated layer is exposed externally.

Claims 8-10 (Cancelled).

Claim 11 (Previously Presented): A method of manufacturing a battery pack according to claim 4, further comprising the step of:

- stamping out a rigid-type integral board along each area thereof, on which the circuit board is to be formed, with a mold.

Claim 12 (Cancelled).